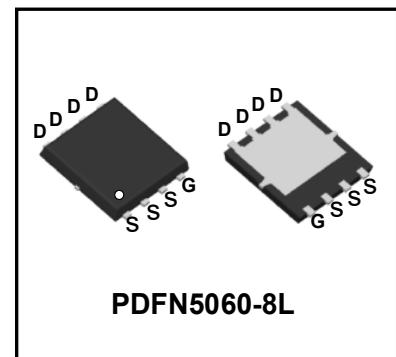


# WMB080N10LG2

## 100V N-Channel Enhancement Mode Power MOSFET

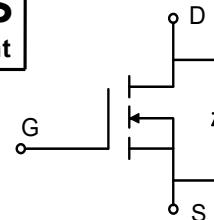
### Description

WMB080N10LG2 uses Wayon's 2<sup>nd</sup> generation power trench MOSFET technology that has been especially tailored to minimize the on-state resistance and yet maintain superior switching performance. This device is well suited for high efficiency fast switching applications.



### Features

- $V_{DS} = 100V$ ,  $I_D = 74A$
- $R_{DS(on)} < 8m\Omega$  @  $V_{GS} = 10V$
- $R_{DS(on)} < 11m\Omega$  @  $V_{GS} = 4.5V$
- Green Device Available
- 100% EAS Guaranteed
- Optimized for High Speed Smooth Switching



### Applications

- Power Management Switches
- DC/DC Converters
- Synchronous Rectification

### Absolute Maximum Ratings ( $T_A = 25^\circ C$ , unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	$V_{DS}$	100	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Continuous Drain Current $T_C=25^\circ C$	$I_D$	74	A
$T_C=100^\circ C$		46.8	
Pulsed Drain Current <sup>1</sup>	$I_{DM}$	296	A
Single Pulse Avalanche Energy <sup>2</sup>	$EAS$	88.2	mJ
Total Power Dissipation	$P_D$	84	W
Operating Junction and Storage Temperature Range	$T_J, T_{STG}$	-55 to 150	$^\circ C$

### Thermal Characteristics

Parameter	Symbol	Value	Unit
Thermal Resistance from Junction-to-Ambient <sup>3</sup>	$R_{\theta JA}$	50	$^\circ C/W$
Thermal Resistance from Junction-to-Case	$R_{\theta JC}$	1.48	$^\circ C/W$

**Electrical Characteristics (T<sub>J</sub> = 25°C, unless otherwise noted)**

Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static Characteristics</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>D</sub> = 250μA	100	-	-	V
Gate-Body Leakage Current	I <sub>GS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current T <sub>J</sub> =25°C	I <sub>DS</sub>	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	1	μA
T <sub>J</sub> =100°C			-	-	100	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.2	1.8	2.4	V
Drain-Source on-Resistance <sup>4</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 20A	-	6.3	8	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 10A		7.8	11	
Forward Transconductance <sup>4</sup>	g <sub>f</sub>	V <sub>DS</sub> = 5V, I <sub>D</sub> = 10A	-	56	-	S
<b>Dynamic Characteristics<sup>5</sup></b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = 50V, V <sub>GS</sub> = 0V, f = 1MHz	-	1920	-	pF
Output Capacitance	C <sub>oss</sub>		-	359	-	
Reverse Transfer Capacitance	C <sub>rss</sub>		-	9.7	-	
Gate Resistance	R <sub>G</sub>	f = 1MHz	-	1.0	-	Ω
<b>Switching Characteristics<sup>5</sup></b>						
Total Gate Charge	Q <sub>g</sub>	V <sub>GS</sub> = 10V, V <sub>DS</sub> = 50V, I <sub>D</sub> = 20A	-	30.8	-	nC
Gate-Source Charge	Q <sub>gs</sub>		-	4.9	-	
Gate-Drain Charge	Q <sub>gd</sub>		-	7.1	-	
Turn-on Delay Time	t <sub>d(on)</sub>	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 50V, R <sub>G</sub> = 3Ω, I <sub>D</sub> = 20A	-	5.8	-	ns
Rise Time	t <sub>r</sub>		-	3.2	-	
Turn-off Delay Time	t <sub>d(off)</sub>		-	18.7	-	
Fall Time	t <sub>f</sub>		-	4.2	-	
Body Diode Reverse Recovery Time	t <sub>rr</sub>	I <sub>F</sub> = 20A, dI/dt = 500A/μs	-	36	-	ns
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>		-	178	-	nC
<b>Drain-Source Body Diode Characteristics</b>						
Diode Forward Voltage <sup>4</sup>	V <sub>SD</sub>	I <sub>S</sub> = 1A, V <sub>GS</sub> = 0V	-	-	1.2	V
Continuous Source Current   T <sub>C</sub> =25°C	I <sub>S</sub>	-	-	-	74	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature T<sub>J(MAX)</sub>=150°C.
2. The test condition is V<sub>DD</sub>=25V, V<sub>GS</sub>=10V, L=0.4mH, I<sub>AS</sub>=21A.
3. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper, The value in any given application depends on the user's specific board design.
4. The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%.
5. This value is guaranteed by design hence it is not included in the production test..

## Typical Characteristics

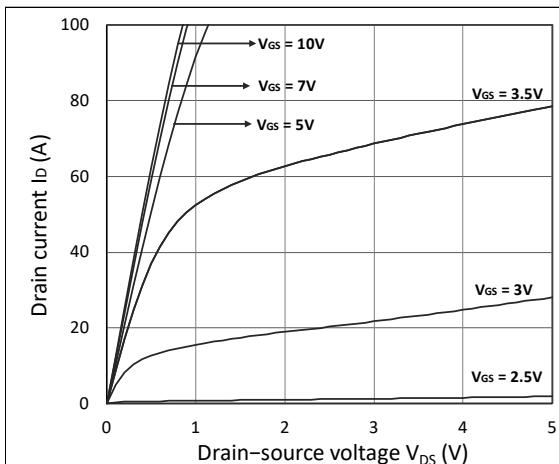


Figure 1. Output Characteristics

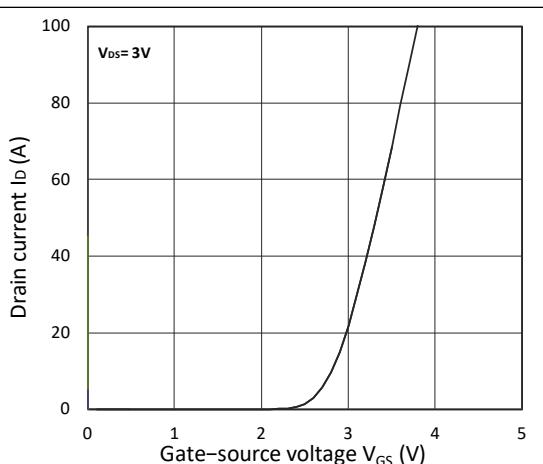


Figure 2. Transfer Characteristics

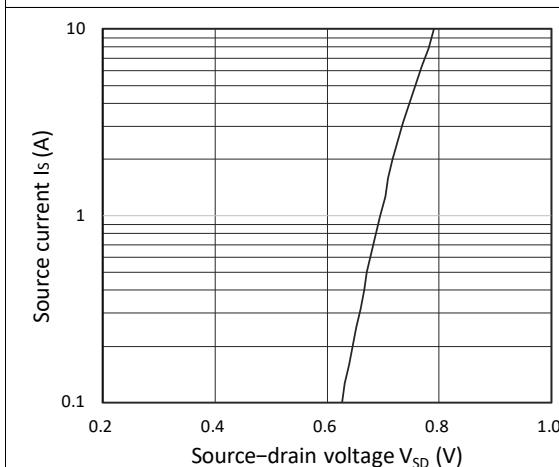
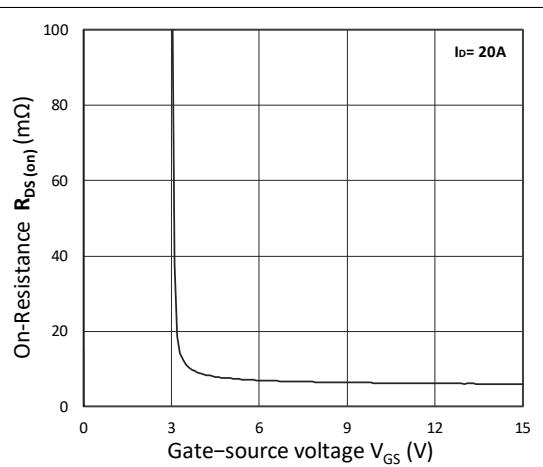
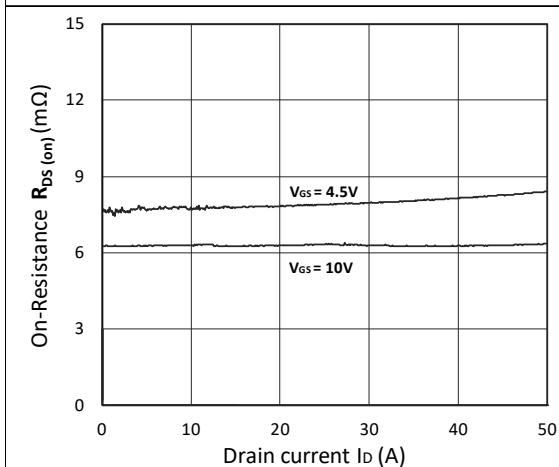
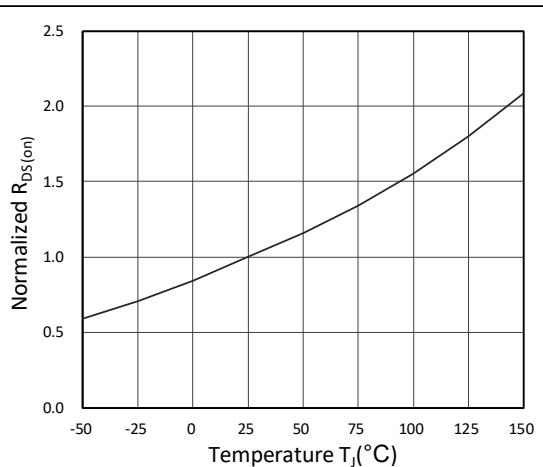


Figure 3. Forward Characteristics of Reverse

Figure 4.  $R_{DS(ON)}$  vs.  $V_{GS}$ Figure 5.  $R_{DS(ON)}$  vs.  $I_D$ Figure 6. Normalized  $R_{DS(ON)}$  vs. Temperature

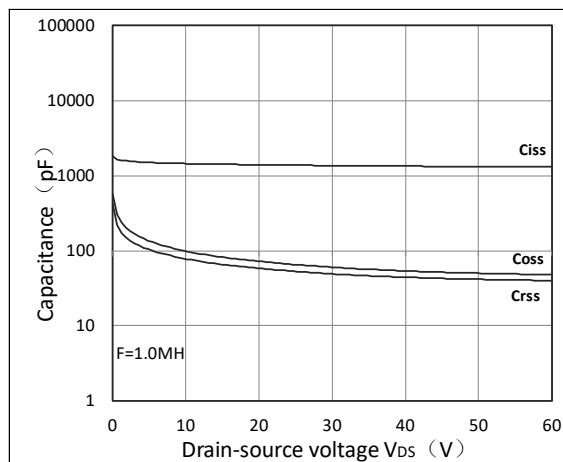


Figure 7. Capacitance Characteristics

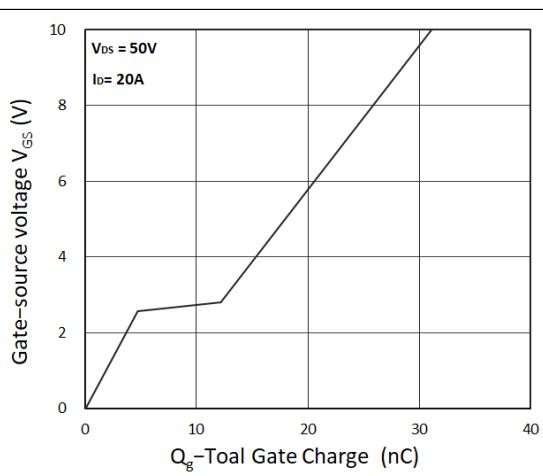


Figure 8. Gate Charge Characteristics

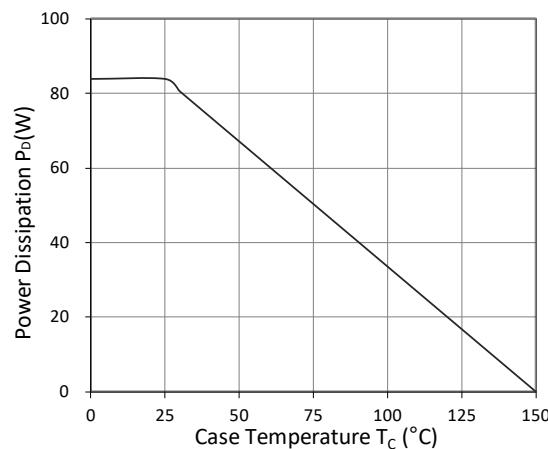


Figure 9. Power Dissipation

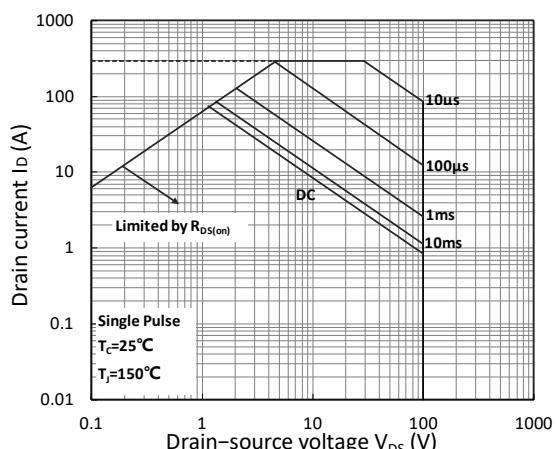


Figure 10. Safe Operating Area

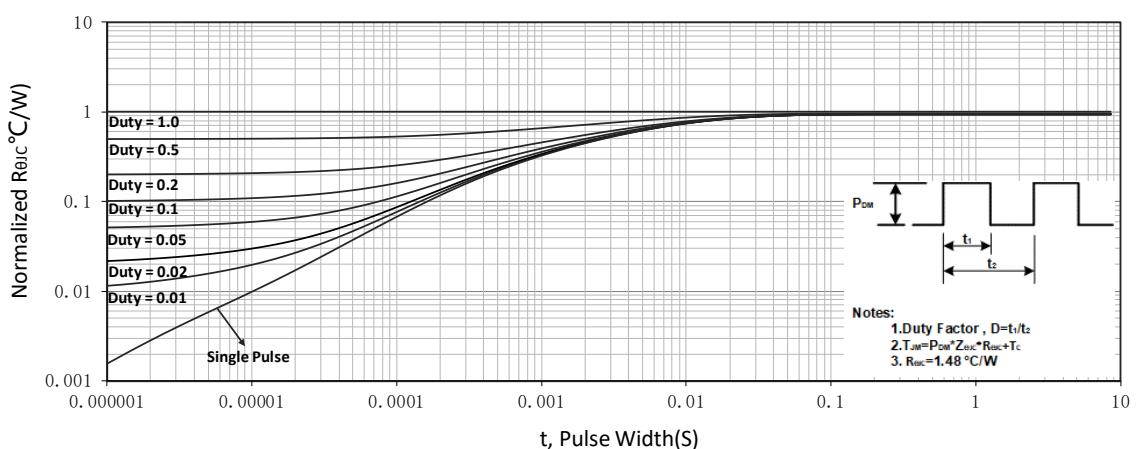
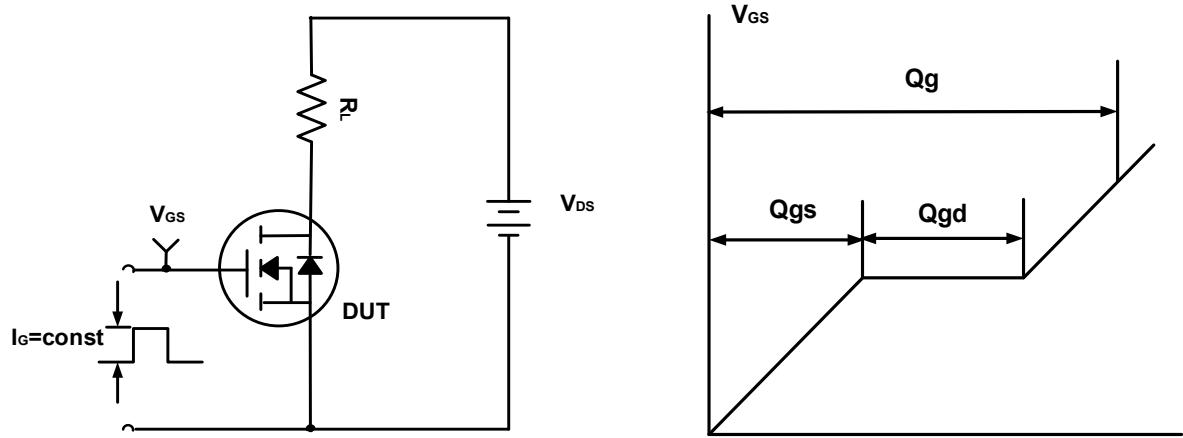
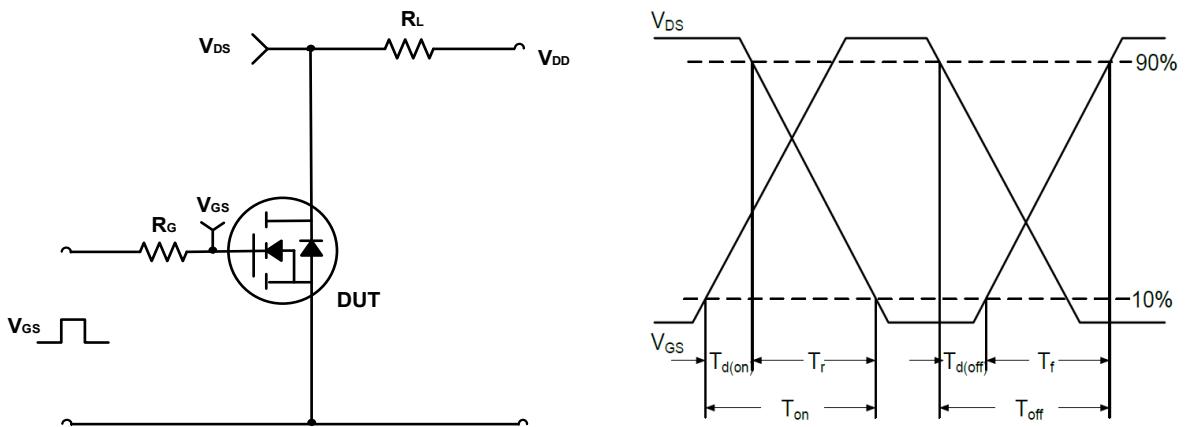
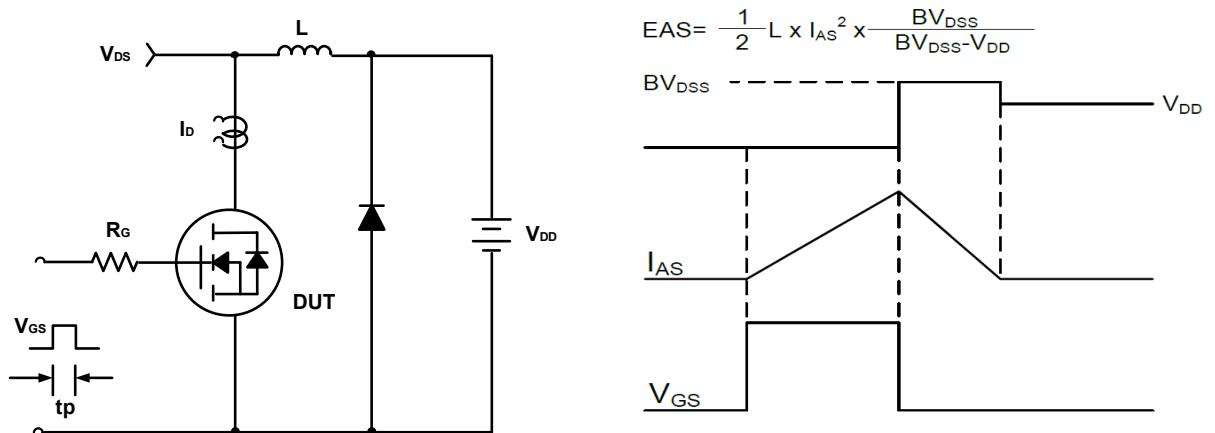


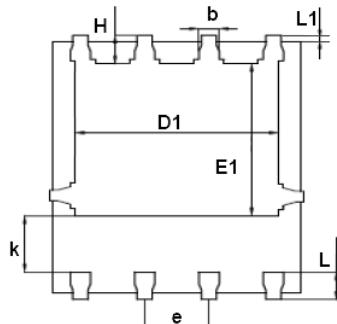
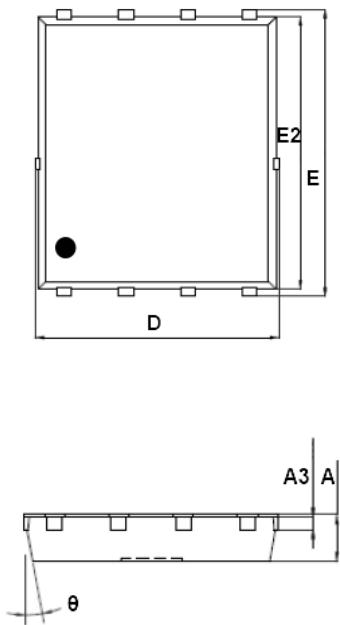
Figure 11. Normalized Maximum Transient Thermal Impedance

**Test Circuit****Figure A. Gate Charge Test Circuit & Waveforms****Figure B. Switching Test Circuit & Waveforms****Figure C. Unclamped Inductive Switching Circuit & Waveforms**

# WMB080N10LG2

## Mechanical Dimensions for PDFN5060-8L

### COMMON DIMENSIONS



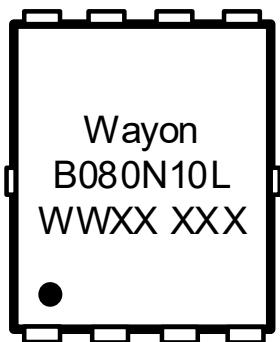
SYMBOL	MM	
	MIN	MAX
A	0.90	1.20
A3	0.15	0.35
D	4.80	5.40
E	5.90	6.35
D1	3.61	4.31
E1	3.30	3.92
E2	5.50	6.06
k	1.10	-
b	0.30	0.51
e	1.27BSC	
L	0.38	0.71
L1	0.05	0.36
H	0.38	0.71
$\theta$	$0^\circ$	$12^\circ$

## **WMB080N10LG2**

### **Ordering Information**

<b>Part</b>	<b>Package</b>	<b>Marking</b>	<b>Packing method</b>
WMB080N10LG2	PDFN5060-8L	B080N10L	Tape and Reel

### **Marking Information**



**B080N10L = Device code**

**WWXX XXX= Date code**